



DECLARATION FOR U.S. PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

PHOTOLINKER MACROMOLECULES, METALLIC SUBSTRATES AND LIGANDS MODIFIED WITH SAID LINKERS, AND PROCESS OF PREPARATION THEREOF

the specification of which is attached hereto unless the following is checked

☒ was filed on _____ as United States Application Number _____ and was filed on 23 NOVEMBER 2004 as PCT International Application Number PCT/CH2004/000704 and was amended on _____ (if applicable).

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claim(s), as amended by any amendment referred above.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 (a) – (d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application for which priority is claimed.

(List prior foreign applications. See note A)

03405851.1 (Number)	EPO (Country)	28 NOV. 2003 (Day/Month/Year Filed)	Priority Claimed <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day/Month/Year Filed)	<input type="checkbox"/> Yes <input type="checkbox"/> No

(See note B) ☐ See attached list for additional prior foreign applications

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

(List prior U.S. Applications)

Status

_____ (Application Serial No.)	_____ (Filing Date)	<input type="checkbox"/> Patented <input type="checkbox"/> Pending <input type="checkbox"/> Abandoned
_____ (Application Serial No.)	_____ (Filing Date)	<input type="checkbox"/> Patented <input type="checkbox"/> Pending <input type="checkbox"/> Abandoned
_____ (Application Serial No.)	_____ (Filing Date)	<input type="checkbox"/> Patented <input type="checkbox"/> Pending <input type="checkbox"/> Abandoned
_____ (Application Serial No.)	_____ (Filing Date)	<input type="checkbox"/> Patented <input type="checkbox"/> Pending <input type="checkbox"/> Abandoned

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

Customer Number: 38834

Please direct all communications to the following address:

Westerman, Hattori, Daniels & Adrian, LLP
1250 Connecticut Avenue, N.W., Suite 700, Washington, D.C. 20036

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(See note C)

Full name of sole or first inventor (given name, family name)

Hans SIGRIST

Inventor's signature

Hans Sigrist

Date

05/10/2006

Residence

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Citizenship

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Hans Sigrist

Full name of second inventor (given name, family name)

Hui CHAI GAO

Inventor's signature

Hui Chai-Gao

Date

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Citizenship

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Full name of third inventor (given name, family name)

Isabelle SOURY-LAVERGNE

Inventor's signature

Isabelle CAELEN SOURY-LAVERGNE

Date

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Residence

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Citizenship

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Isabelle Caelen Soury-Lavergne

Full name of fourth inventor (given name, family name)

Inventor's signature

Date

Residence

Citizenship

Post Office Address

Full name of fifth inventor (given name, family name)

Inventor's signature

Date

Residence

Citizenship

Post Office Address

Full name of sixth inventor (given name, family name)

Inventor's signature

Date

Residence

Citizenship

Post Office Address

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar (\$1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by
C.S.E.M Centre Suisse d'Electronique et de Microtechnique

(Insert ASSIGNEE's
Name(s) Address(es))

1, rue Jaquet-Droz

CH - 2007 Neuchâtel, Switzerland

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of Invention)

**PHOTOLINKER MACROMOLECULES, METALLIC SUBSTRATES AND LIGANDS
MODIFIED WITH SAID LINKERS, AND PROCESS OF PREPARATION
THEREOF**

(*If the assignment is
being filed after the
filing of the
application, this
section must be
completed)

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

* filed on _____ Serial No. _____

(Westerman, Hattori, Daniels & Adrian, LLP is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefore on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with the application and any continuation, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

(Signatures)

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

<u>Hans Sigrist</u> (Signature)	<u>Hans SIGRIST</u> (Type Name)	<u>05/10/2006</u> (Date)
<u>Hui Chai Gao</u> (Signature)	<u>Hui CHAI GAO</u> (Type Name)	<u>05/10/2006</u> (Date)
<u>Isabelle Gaelen Soury-Lavergne</u> (Signature)	<u>Isabelle SOURY-LAVERGNE</u> (Type Name)	<u>05/10/2006</u> (Date)
_____ (Signature)	_____ (Type Name)	_____ (Date)
_____ (Signature)	_____ (Type Name)	_____ (Date)
_____ (Signature)	_____ (Type Name)	_____ (Date)

NO LEGALIZATION REQUIRED